Glass Wafer for CSP

Alkali-free and polish-free glass wafer featuring low CTE* is used as cover glass for WLCSP (Wafer Level Chip Size Package) of CMOS image sensors.

*CTE: coefficient of thermal expansion

Features

- Alkali-free and polish-free
- As-free, Sb-free characteristics are eco-friendly.
- Excellent surface quality
- Available in various thin film coatings such as AR and metal.

Properties

Properties/Glass Code			**ABC-1**
Coefficient of thermal expansion	30-380°C	$\times 10^{-7}$/K	37
Density		$\times 10^3$kg/m^3	2.52
Young's modulus		GPa	78
Poisson's ratio			0.2
Volume resistivity Log ρ	350℃	Ω·cm	13.0
Dielectric constant	1MHz, RT		5.6
tan δ	1MHz, RT		0.001
Refractive index(n_d)	587.6nm	%	1.53
Light transmittance	λ=550nm	%	92

Configuration Image of Smartphone Camera